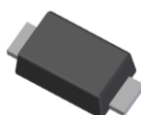


## Features and Benefits

- Glass Passivated Die Construction
- Super-Fast Recovery Time for High Efficiency
- ±2kV ESD Protection (IEC61000-4-2, Contact Discharge)
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

## Mechanical Data

- Case: PowerDI® 123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 ③
- Weight: 0.01 grams (Approximate)



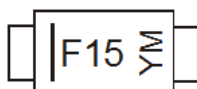
Top View

## Ordering Information (Note 4)

| Device     | Packaging  | Shipping         |
|------------|------------|------------------|
| DFLU1200-7 | PowerDI123 | 3000/Tape & Reel |

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



F15 = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: E = 2017)  
 M = Month (ex: 9 = September)

### Date Code Key

| Year  | 2005 | ... | 2013 | 2014 | 2015 | 2016 | 2017 | 2018 | 2019 | 2020 | 2021 | 2022 |
|-------|------|-----|------|------|------|------|------|------|------|------|------|------|
| Code  | S    | ... | A    | B    | C    | D    | E    | F    | G    | H    | I    | J    |
| Month | Jan  | Feb | Mar  | Apr  | May  | Jun  | Jul  | Aug  | Sep  | Oct  | Nov  | Dec  |
| Code  | 1    | 2   | 3    | 4    | 5    | 6    | 7    | 8    | 9    | O    | N    | D    |

## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

| Characteristic                                                                                      | Symbol              | Value | Unit |
|-----------------------------------------------------------------------------------------------------|---------------------|-------|------|
| Peak Repetitive Reverse Voltage                                                                     | V <sub>RRM</sub>    | 200   | V    |
| Working Peak Reverse Voltage                                                                        | V <sub>RWM</sub>    |       |      |
| DC Blocking Voltage                                                                                 | V <sub>R</sub>      |       |      |
| RMS Reverse Voltage                                                                                 | V <sub>R(RMS)</sub> | 140   | V    |
| Average Rectified Output Current (See Figure 4)                                                     | I <sub>O</sub>      | 1.0   | A    |
| Non-Repetitive Peak Forward Surge Current 8.3ms<br>Single Half Sine-Wave Superimposed on Rated Load | I <sub>FSM</sub>    | 30    | A    |

## Thermal Characteristics

| Characteristic                                                           | Symbol                            | Typ         | Max | Unit |
|--------------------------------------------------------------------------|-----------------------------------|-------------|-----|------|
| Power Dissipation (Note 6) @ T <sub>A</sub> = +25°C                      | P <sub>D</sub>                    | —           | 1.0 | W    |
| Thermal Resistance Junction to Soldering Point (Note 7)                  | R <sub>θJS</sub>                  | —           | 6   | °C/W |
| Thermal Resistance Junction to Ambient (Note 6) @ T <sub>A</sub> = +25°C | R <sub>θJA</sub>                  | 116         | —   | °C/W |
| Thermal Resistance Junction to Ambient (Note 8) @ T <sub>A</sub> = +25°C | R <sub>θJA</sub>                  | 182         | —   | °C/W |
| Operating and Storage Temperature Range                                  | T <sub>J</sub> , T <sub>STG</sub> | -65 to +150 |     | °C   |

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic                                                  | Symbol            | Value | Unit |
|-----------------------------------------------------------------|-------------------|-------|------|
| Minimum Reverse Breakdown Voltage @ I <sub>R</sub> = 5μA        | V <sub>(BR)</sub> | 200   | V    |
| Maximum Forward Voltage Drop @ I <sub>F</sub> = 0.6A            | V <sub>FM</sub>   | 0.90  | V    |
| @ I <sub>F</sub> = 1.0A                                         |                   | 0.98  |      |
| Peak Reverse Current @ T <sub>A</sub> = +25°C                   | I <sub>RM</sub>   | 5.0   | μA   |
| at Rated DC Blocking Voltage (Note 5) @ T <sub>A</sub> = +100°C |                   | 200   |      |
| Reverse Recovery Time (Note 9)                                  | t <sub>RR</sub>   | 25    | ns   |
| Typical Total Capacitance (f = 1MHz, V <sub>R</sub> = 4VDC)     | C <sub>T</sub>    | 27    | pF   |

- Notes:
5. Short duration pulse test used to minimize self-heating effect.
  6. Device mounted on 1" x 1", Polyimide PCB; 2 oz. Cu pad layout as shown on Diodes Incorporated's website <http://www.diodes.com/package-outlines.html>.
  7. Theoretical R<sub>θJS</sub> calculated from the top center of the die straight down to the PCB cathode tab solder junction.
  8. Device mounted on FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/package-outlines.html>.
  9. Measured with I<sub>F</sub> = 0.5A, I<sub>R</sub> = 1.0A, I<sub>RR</sub> = 0.25A. See figure 7.

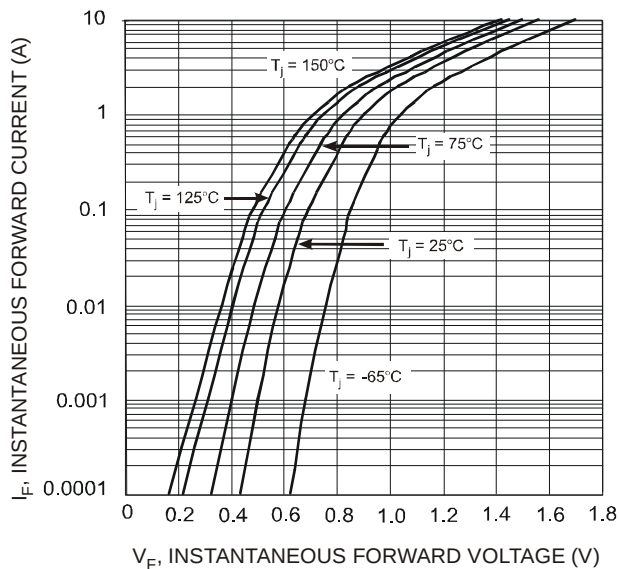


Fig. 1 Typical Forward Characteristics

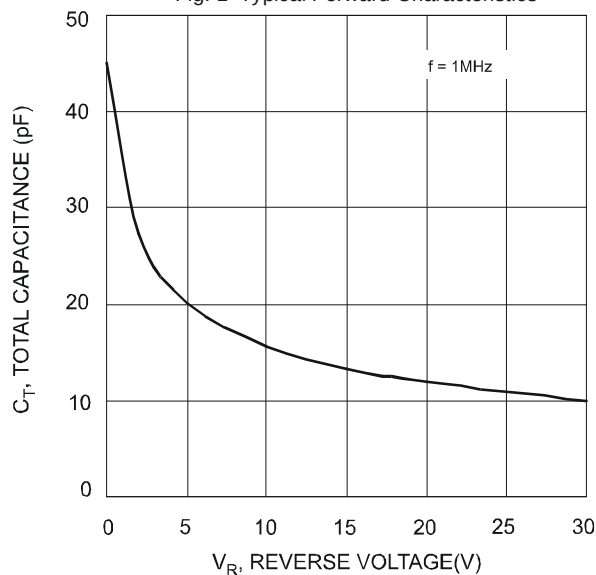


Fig. 3 Typical Total Capacitance

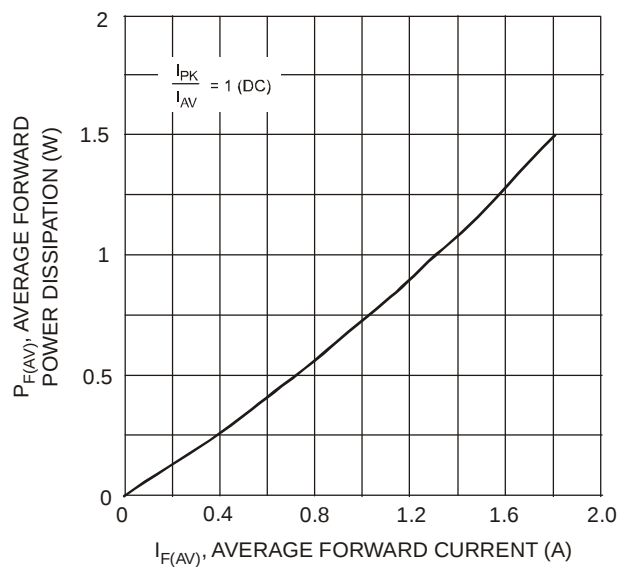


Fig. 5 Forward Power Dissipation

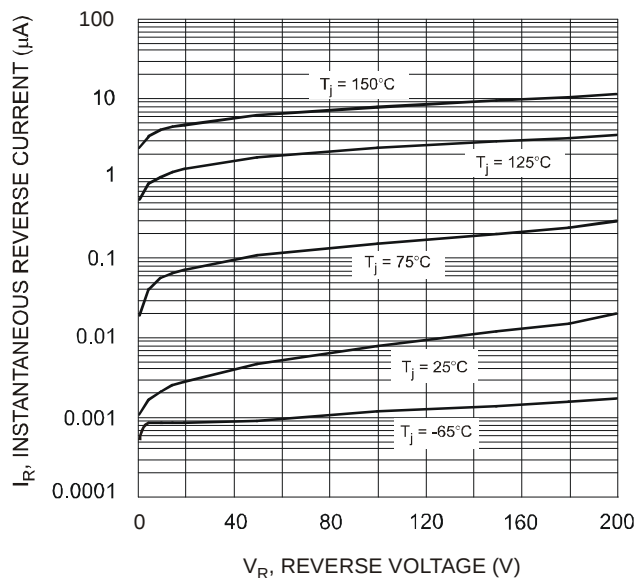


Fig. 2 Typical Reverse Characteristics

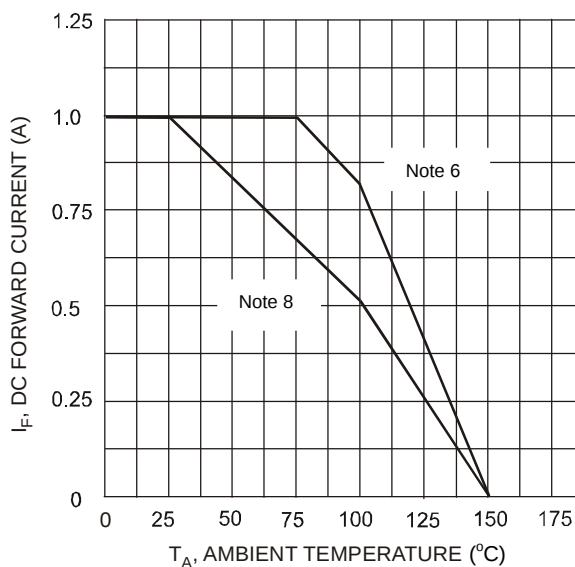


Fig. 4 DC Forward Current Derating

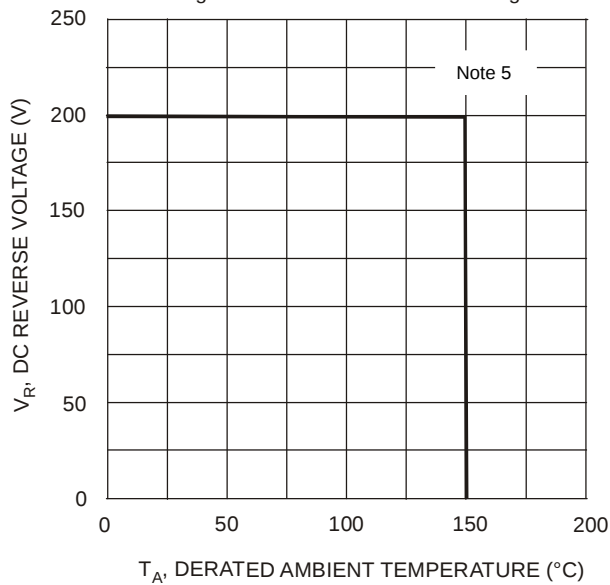
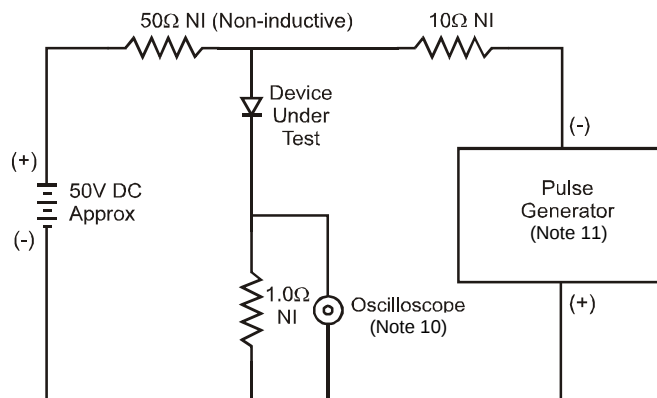
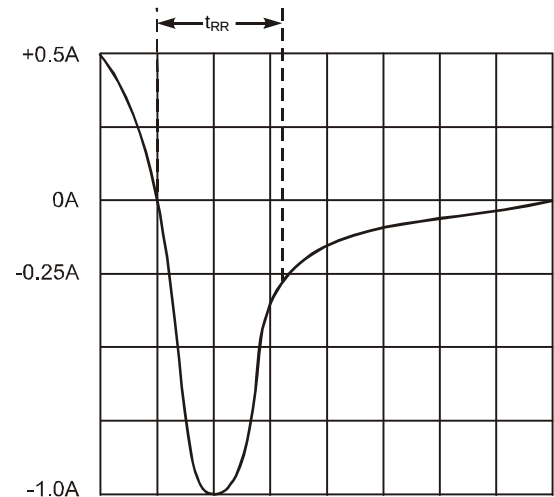


Fig. 6 Operating Temperature Derating



Notes:  
 10. Rise Time=7.0ns max. Input Impedance=1.0MΩ. 22pF.  
 11. Rise Time=10ns max. Input Impedance=50Ω.



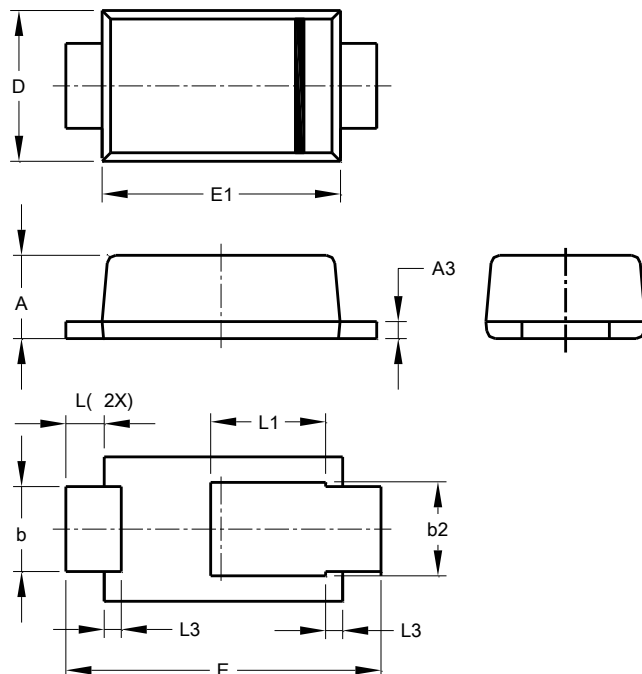
Set time base for 50/100 ns/cm

Fig. 7 Reverse Recovery Time Characteristic and Test Circuit

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**PowerDI123**

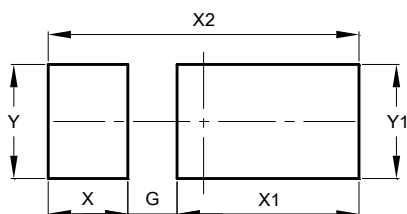


| PowerDI123           |       |       |      |
|----------------------|-------|-------|------|
| Dim                  | Min   | Max   | Typ  |
| A                    | 0.93  | 1.00  | 0.98 |
| A3                   | 0.15  | 0.25  | 0.20 |
| b                    | 0.85  | 1.25  | 1.00 |
| b2                   | 1.025 | 1.125 | 1.10 |
| D                    | 1.63  | 1.93  | 1.78 |
| E                    | 3.50  | 3.90  | 3.70 |
| E1                   | 2.60  | 3.00  | 2.80 |
| L                    | 0.40  | 0.50  | 0.45 |
| L1                   | 1.25  | 1.40  | 1.35 |
| L3                   | 0.125 | 0.275 | 0.20 |
| All Dimensions in mm |       |       |      |

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**PowerDI123**



| Dimensions | Value (in mm) |
|------------|---------------|
| G          | 0.65          |
| X          | 1.05          |
| X1         | 2.40          |
| X2         | 4.10          |
| Y          | 1.50          |
| Y1         | 1.50          |

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